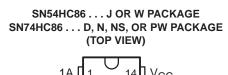
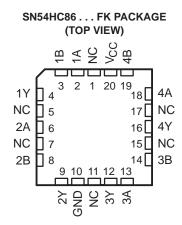
SCLS100E - DECEMBER 1982 - REVISED AUGUST 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-µA Max I_{CC}
- Typical t_{pd} = 10 ns



<u>і~ц</u>	1	14	⊐ vcc
1B [13] 4B
1Y [3] 4A
2A [4	11] 4Y
2B [5	10] 3B
2Y [6	9] 3A
GND [7	8] 3Y

- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- True Logic



NC - No internal connection

description/ordering information

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

ТА	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC86N	SN74HC86N
		Tube of 50	SN74HC86D	
	SOIC – D	Reel of 2500	SN74HC86DR	HC86
–40°C to 85°C		Reel of 250	SN74HC86DT	
	SOP – NS	Reel of 2000	SN74HC86NSR	HC86
		Tube of 90	SN74HC86PW	
	TSSOP – PW	Reel of 2000	SN74HC86PWR	HC86
		Reel of 250	SN74HC86PWT	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC86J	SNJ54HC86J
	CFP – W	Tube of 150	SNJ54HC86W	SNJ54HC86W
	LCCC – FK	Tube of 55	SNJ54HC86FK	SNJ54HC86FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



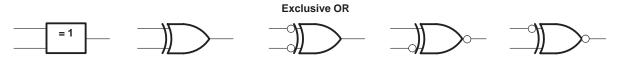
Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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FUNCTION TABLE (each gate)					
INPUTS OUTPUT					
Α	В	Y			
L	L	L			
L	Н	н			
н	L	н			
н	Н	L			

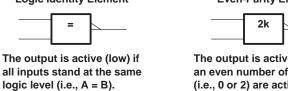
exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

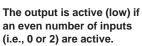


These are five equivalent exclusive-OR symbols valid for an 'HC86 gate in positive logic; negation may be shown at any two ports.

Logic Identity Element









2k + 1 The output is active (high) if

an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		. -0.5 V to 7 V
Input clamp current, I_{IK} (V _I < 0 or V _I > V _{CC}) (se	ee Note 1)	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CO}	c) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	-	±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	: D package	86°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			S	SN54HC86		SN74HC86			UNIT
			MIN NOM MAX MIN N			NOM	MAX		
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
V_{IH}	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		$V_{CC} = 2 V$			0.5			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35			1.35	V
		ACC = 6 A			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$			1000			1000	
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 4.5 V$			500			500	ns
		VCC = 6 V			400			400	
Тд	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	RAMETER TEST CONDITIONS		Vaa	Т	A = 25°C	;	SN54HC86		SN74HC86		
FARAMETER			Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
		I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
V _{OL}	$V_I = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
Ц	$V_{I} = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_{I} = V_{CC} \text{ or } 0,$	l _O = 0	6 V			2		40		20	μΑ
Ci			2 V to 6 V		3	10		10		10	pF



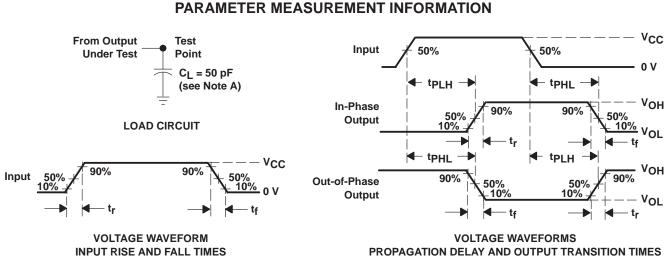
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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vee	Τ,	λ = 25°C	;	SN54	HC86	SN74	IC86	UNIT							
FARAMETER	(OUTPUT) (OUTPUT)		Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT							
			2 V		40	100		150		125								
^t pd	A or B	Y	4.5 V		12	20		30		25	ns							
										6 V		10	17		25		21	
			2 V		28	75		110		95								
tt		Y	Y	Y	Y	Y	4.5 V		8	15		22		19	ns			
			6 V		6	13		19		16								

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	35	pF



NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns. t_f = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

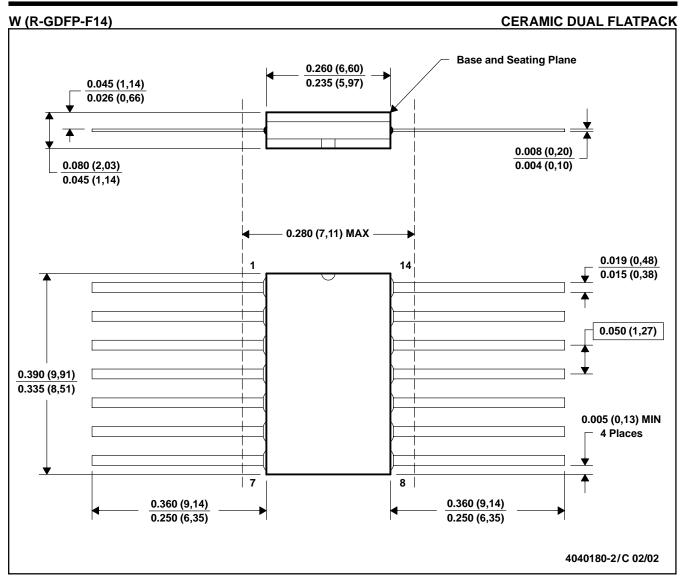


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

MCFP002A - JANUARY 1995 - REVISED FEBRUARY 2002



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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